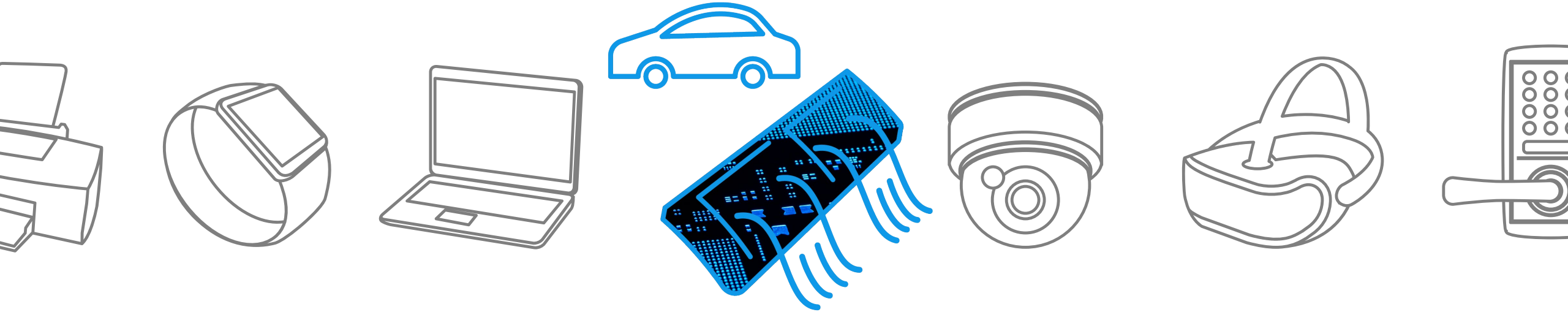
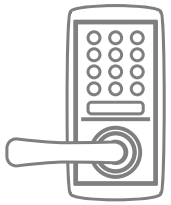
TOSHIBA

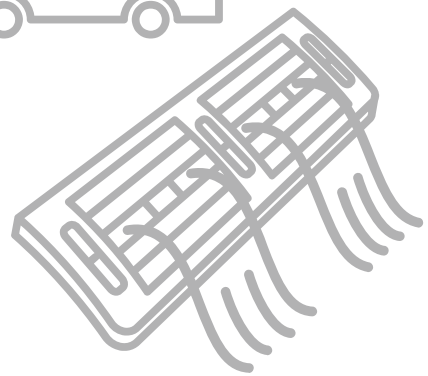
R21

Automotive HVAC

Solution Proposal by Toshiba

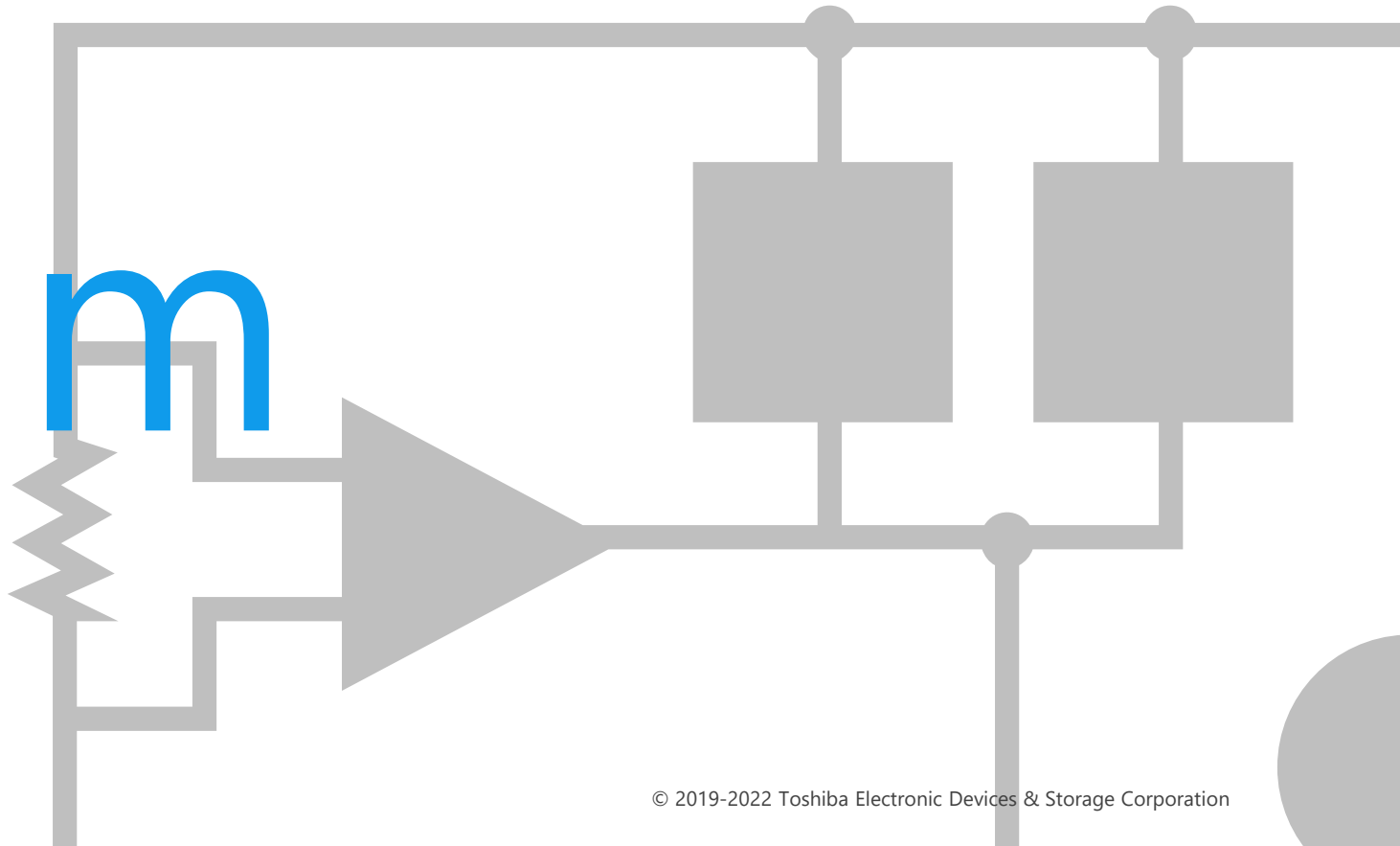




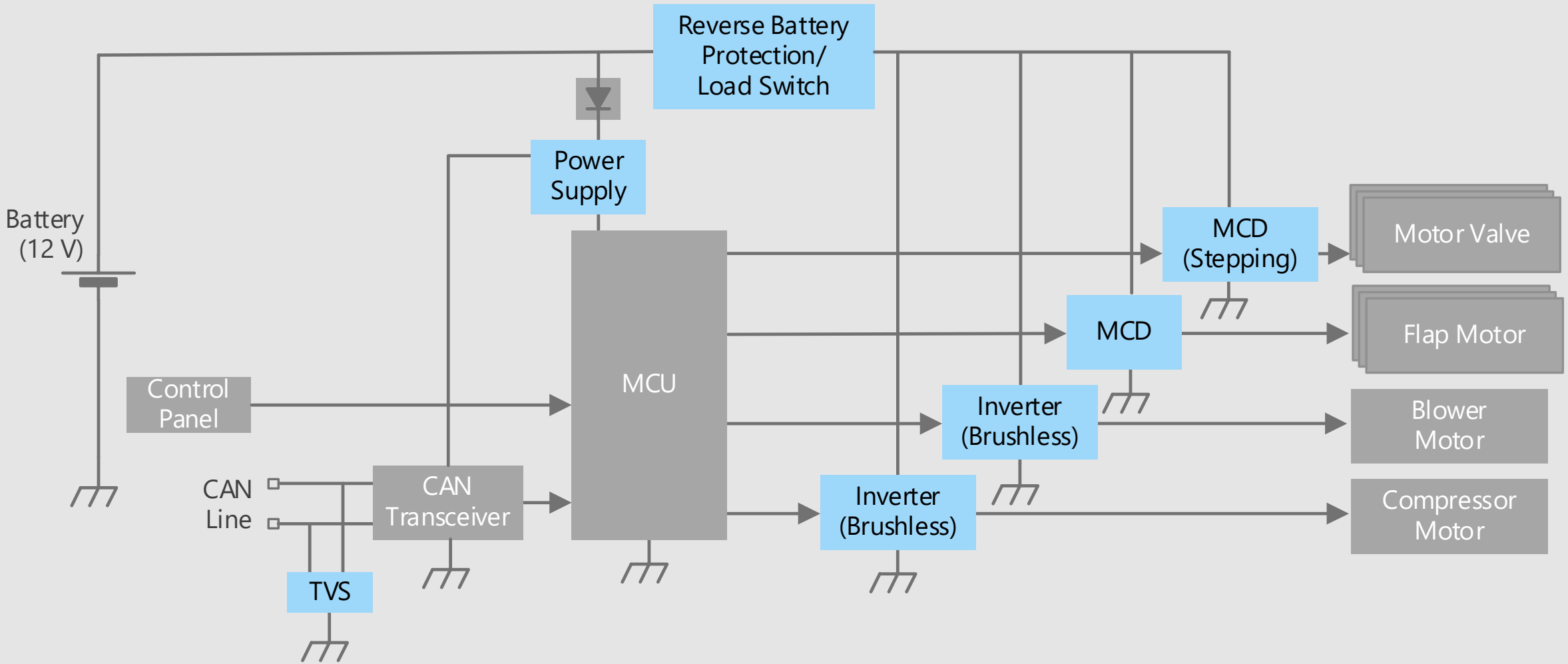


Toshiba Electronic Devices & Storage Corporation provides comprehensive device solutions to customers developing new products by applying its thorough understanding of the systems acquired through the analysis of basic product designs.

Block Diagram

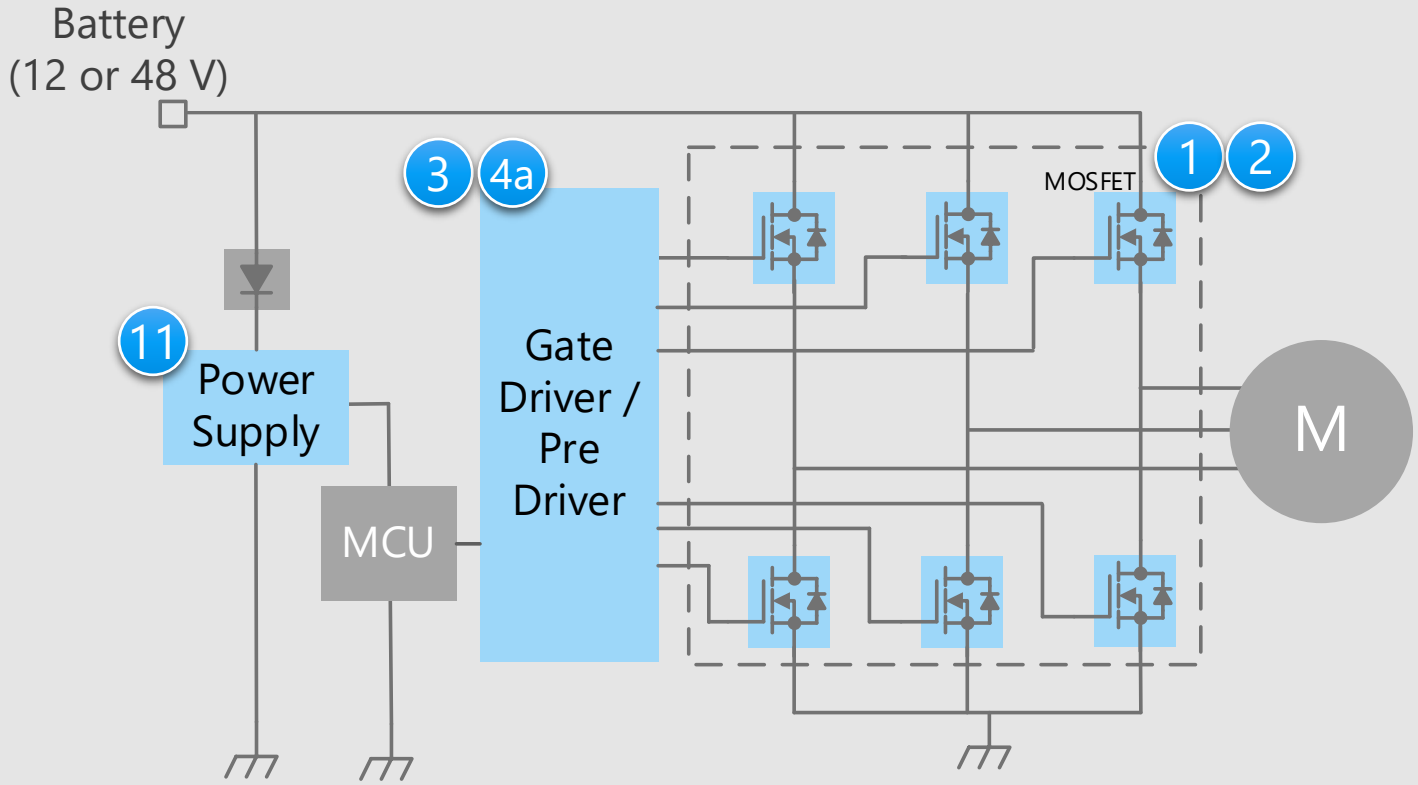


HVAC　Overall block diagram



HVAC　Detail of brushless DC motor drive

Brushless DC motor drive circuit



* Click on the numbers in the circuit diagram to jump to the detailed descriptions page

Criteria for device selection

- It is necessary to select the product with the suitable voltage and current ratings for each application.
- It is necessary to select a gate driver according to the characteristics of the switching device to be driven.
- A small surface mount package is suitable for realizing miniaturization of the ECU.

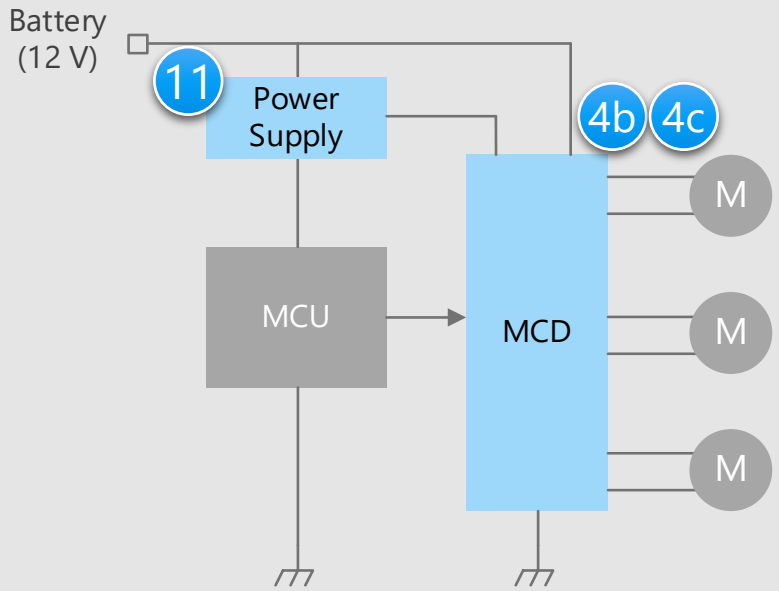
Proposals from Toshiba

- **Low on-resistance contributes to low power consumption of the system**
  U-MOS Series 40 V N-ch MOSFET
  U-MOS Series 100 V N-ch MOSFET
- **Gate driver with built-in protection and diagnosis functions**
  Gate driver (for motor)
- **Noise reduction by sinusoidal wave driving**
  Brushless DC motor pre driver for blower
- **Voltage regulator with low current consumption**
  Power supply IC (for MCU)

1
2
3
4a
11

HVAC　Detail of brushed DC motor drive

Brushed DC motor drive circuit



* Click on the numbers in the circuit diagram to jump to the detailed descriptions page

Criteria for device selection

- The number of parts can be reduced by using the motor control IC with the built-in output driver.
- A small surface mount package is suitable for realizing miniaturization of the ECU.

Proposals from Toshiba

- **Suitable for driving a small brush DC motor**

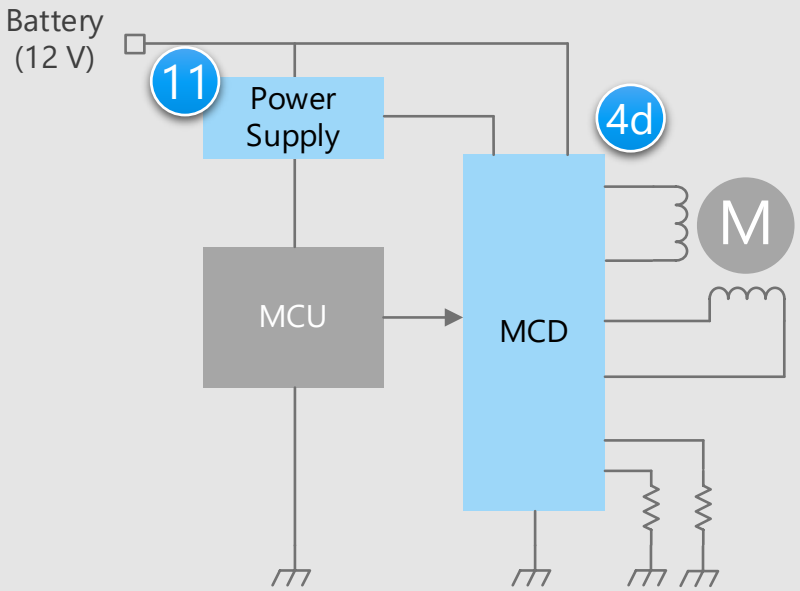
  Brushed DC motor driver for damper 4b 4c

- **Voltage regulator with low current consumption**

  Power supply IC (for MCU) 11

HVAC　Detail of stepping motor drive

Stepping motor drive circuit



* Click on the numbers in the circuit diagram to jump to the detailed descriptions page

Criteria for device selection

- The number of parts can be reduced by using the motor control IC with the built-in output driver.
- A small surface mount package is suitable for realizing miniaturization of the ECU.

Proposals from Toshiba

- **Suitable for a motor valve drive**

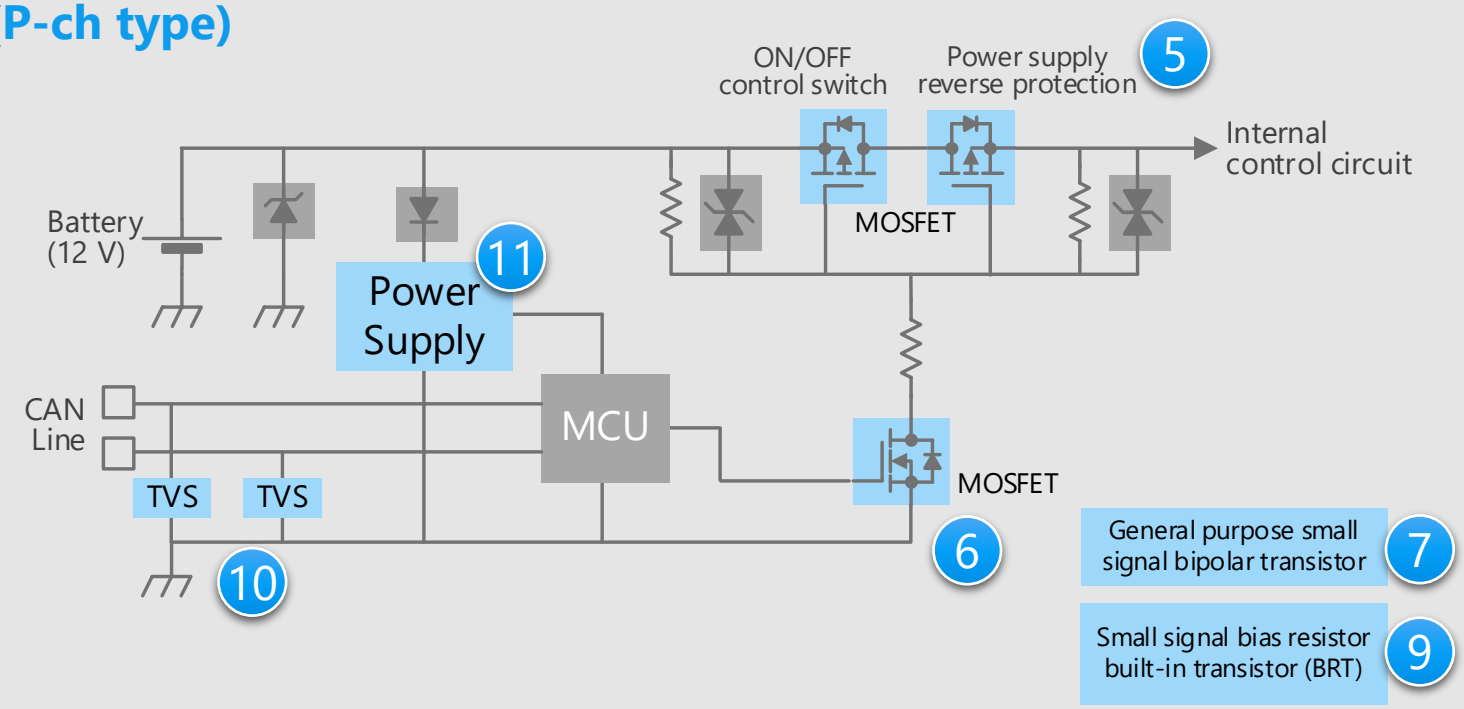
  Stepping motor driver　4d

- **Voltage regulator with low current consumption**

  Power supply IC (for MCU)　11

Detail of switch for power supply ON/OFF control and reverse connection protection (1)

Power supply ON/OFF control and reverse connection protecting circuit (P-ch type)



* Click on the numbers in the circuit diagram to jump to the detailed descriptions page

Criteria for device selection

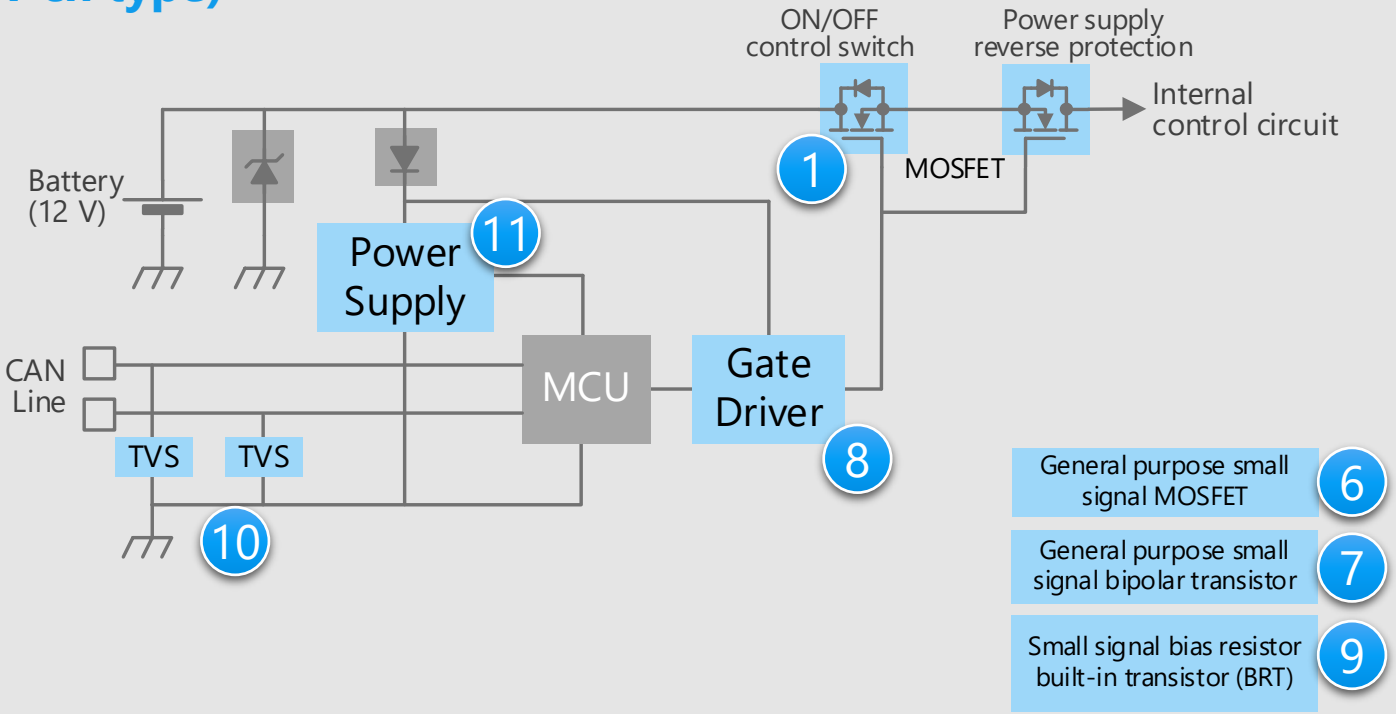
- It is necessary to select the product with the suitable voltage and current ratings for each application.
- It is necessary to select a gate driver according to the characteristics of the switching device to be driven.
- A small surface mount package is suitable for realizing miniaturization of the ECU.

Proposals from Toshiba

- **Low on-resistance contributes to low power consumption of the system**
  U-MOS Series -40 V / -60 V P-ch MOSFET (5)
- **Extensive product lineup**
  General purpose small signal MOSFET (6)
  General purpose small signal bipolar transistor (7)
  Small signal bias resistor built-in transistor (BRT) (9)
- **Suitable for ESD protection**
  TVS diode (for CAN communication) (10)
- **Voltage regulator with low current consumption**
  Power supply IC (for MCU) (11)

Detail of switch for power supply ON/OFF control and reverse connection protection (2)

Power supply ON/OFF control and reverse connection protecting circuit (N-ch type)



* Click on the numbers in the circuit diagram to jump to the detailed descriptions page

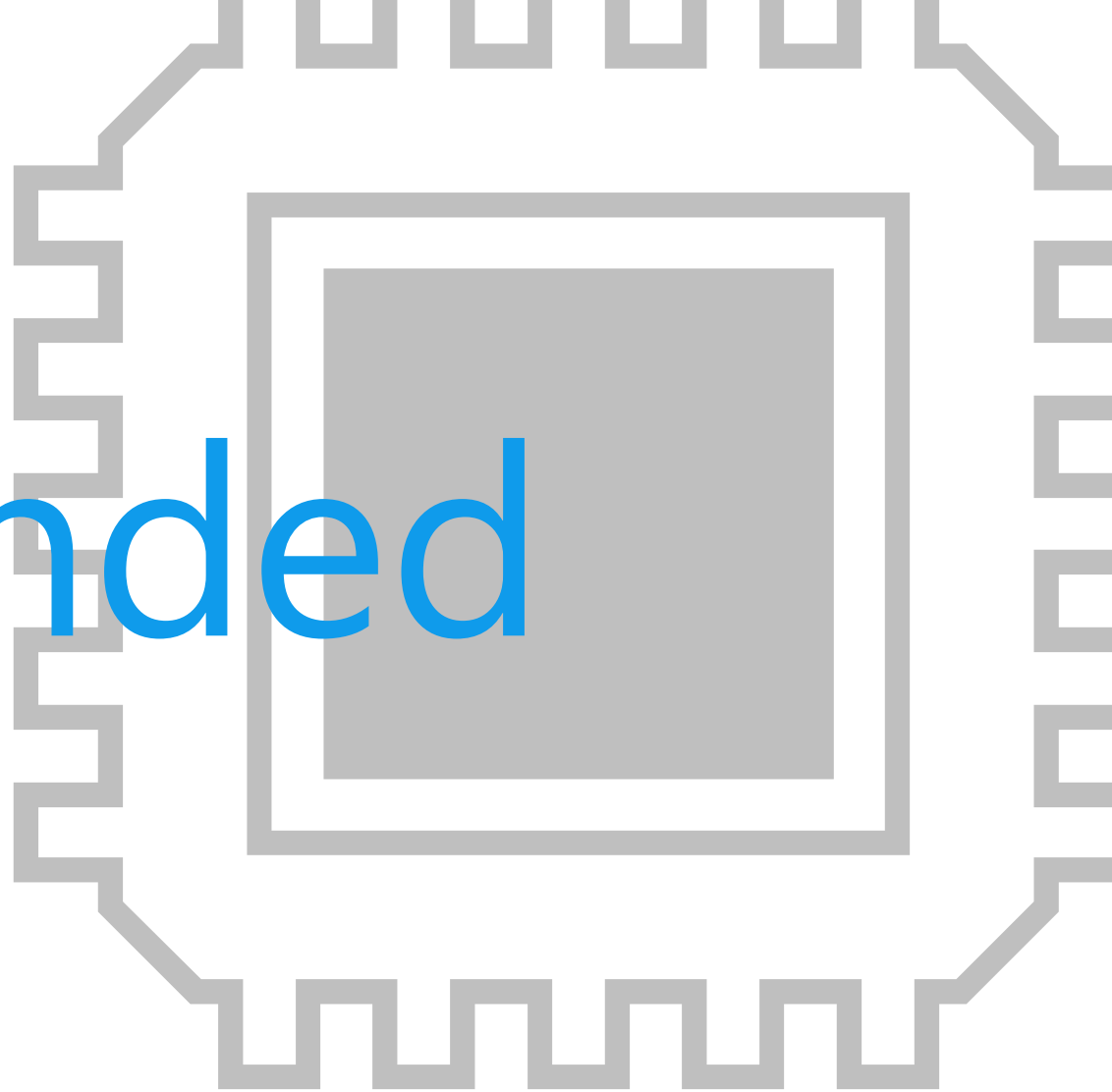
Criteria for device selection

- It is necessary to select the product with the suitable voltage and current ratings for each application.
- It is necessary to select a gate driver according to the characteristics of the switching device to be driven.
- A small surface mount package is suitable for realizing miniaturization of the ECU.

Proposals from Toshiba

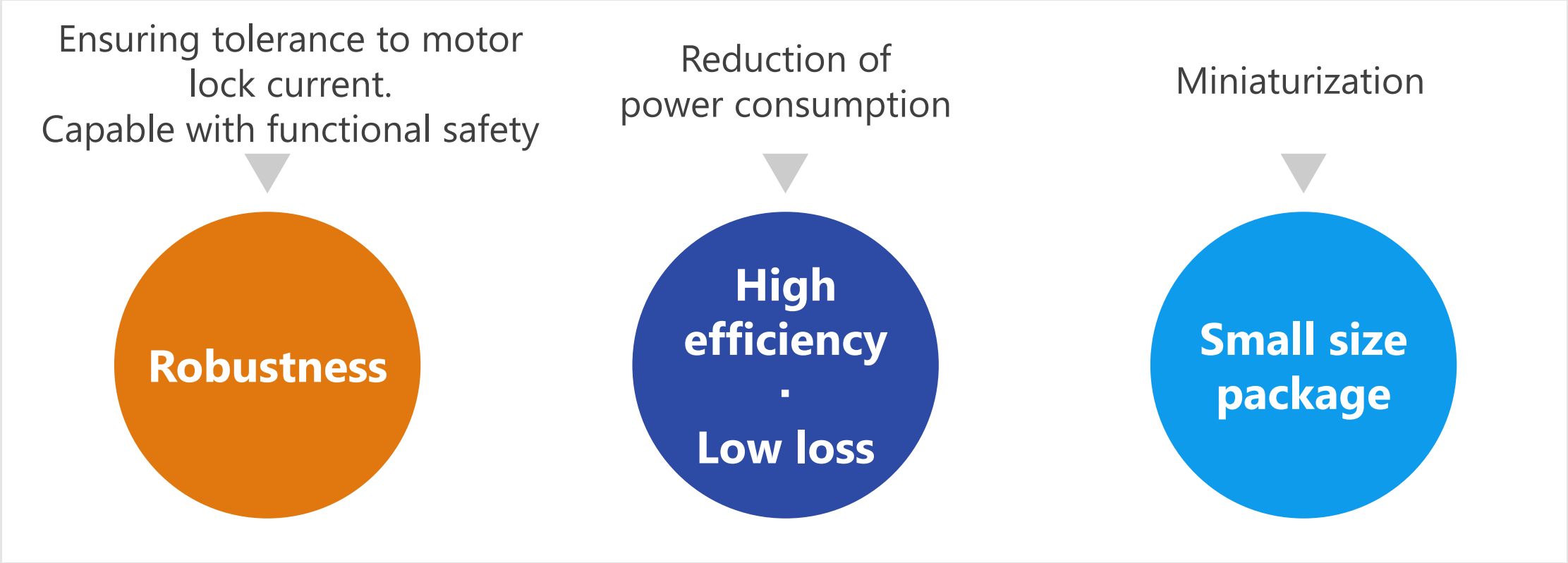
- **Low on-resistance contributes to low power consumption of the system** (1)
  U-MOS Series 40 V N-ch MOSFET
- **Gate driver with built-in protection and diagnosis functions** (8)
  Gate driver (for switch)
- **Extensive product lineup** (6, 7, 9)
  General purpose small signal MOSFET
  General purpose small signal bipolar transistor
  Small signal bias resistor built-in transistor (BRT)
- **Suitable for ESD protection** (10)
  TVS diode (for CAN communication)
- **Voltage regulator with low current consumption** (11)
  Power supply IC (for MCU)

Recommended Devices



Device solutions to address customer needs

As described above, in the design of HVAC, **“Ensuring tolerance to motor lock current. Capable with functional safety”**, **“Reduction of power consumption”** and **“Miniaturization“** are important factors. Toshiba’s proposals are based on these three solution perspectives.



Device solutions to address customer needs

		Robustness	High efficiency · Low loss	Small size package
1	U-MOS Series 40 V N-ch MOSFET	●	●	●
2	U-MOS Series 100 V N-ch MOSFET	●	●	●
3	Gate driver (for motor)	●		●
4	Motor driver *	●	●	
5	U-MOS Series -40 V / -60 V P-ch MOSFET	●	●	●
6	General purpose small signal MOSFET		●	●
7	General purpose small signal bipolar transistor			●
8	Gate driver (for switch)	●		●
9	Small signal bias resistor built-in transistor (BRT)			●
10	TVS diode (for CAN communication)	●		●
11	Power supply IC (for MCU)		●	●

* Damper (LIN communication): TB9056FNG / TB9058FNG, (Direct control type): TB9101FNG / TB9102FNG
* Blower: TB9080FG
* Expansion valves in refrigerant cooling system: TB9120AFTG

1 U-MOS Series 40 V N-ch MOSFET

XPN3R804NC / TK1R4S04PB / XPHR7904PS / TPWR7904PB / XPJ6604PB* / XPQR3004PB

Robustness | High efficiency · Low loss | Small size package

Value provided

The latest processes enables low on-resistance and low noise, thereby reducing power consumption.

1 Low loss (reduced on-resistance)

Using low on-resistance technology to contribute to reduced power consumption systems.
On-resistance of 44 % reduction per unit area.
(compared to Toshiba's U-MOSⅧ-H products)

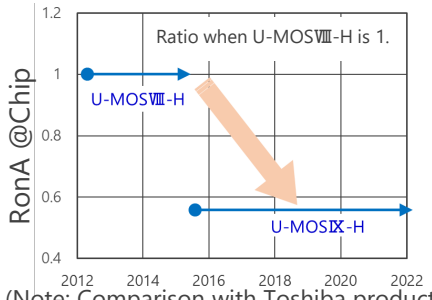
2 Small and low loss package

By adopting a Cu clip structure and a double-sided heat dissipation structure, low loss and high heat dissipation are realized.
Wettable Flank (WF) package contributes to good mountability.

3 Low noise (low EMI)

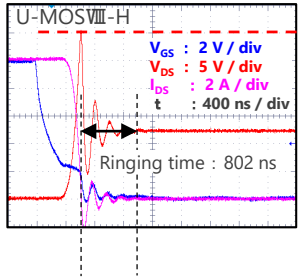
Improved chip process reduces surge voltage and ringing time.

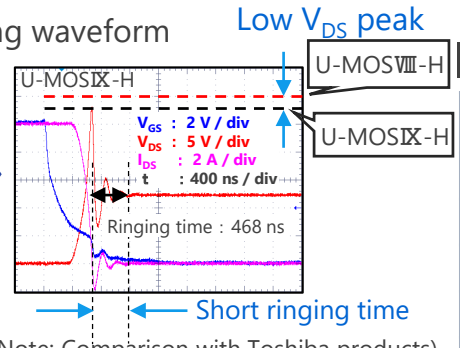
Low loss: RonA trend



(Note: Comparison with Toshiba products)

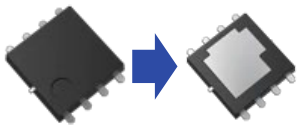
Low noise: Switching waveform





(Note: Comparison with Toshiba products)

DSOP Advance(WF)L double-sided cooling package



Thermal resistance is reduced by 76 % @t = 3 s, mounted on board
Compared to Toshiba's SOP Advance(WF)

S-TOGL™ & L-TOGL™ Cu clip structure

Lineup

Part number	Rated drain current [A]	On-resistance (Max) [mΩ] @V_{GS} = 10 V	Package
XPN3R804NC	40	3.8	TSON Advance(WF)
TK1R4S04PB	120	1.35	DPAK+
XPHR7904PS	150	0.79	SOP Advance(WF)
TPWR7904PB	150	0.79	DSOP Advance(WF)L
XPJR6604PB*	(200)	(0.66)	S-TOGL™
XPQR3004PB	400	0.30	L-TOGL™

* : Under development (Values enclosed in parentheses are tentative specifications. Specifications are subject to change without notice.)

◆Return to Block Diagram TOP

2 U-MOS Series 100 V N-ch MOSFET

XPN1300ANC / XPN2400ANC* / TK60S10N1L / XPH4R10ANB / XPH6R30ANB / XPW4R10ANB / XPW6R30ANB / XPQ1R00AQB*

Robustness | High efficiency · Low loss | Small size package

Value provided

Low on-resistance contributes to reduced system power consumption.

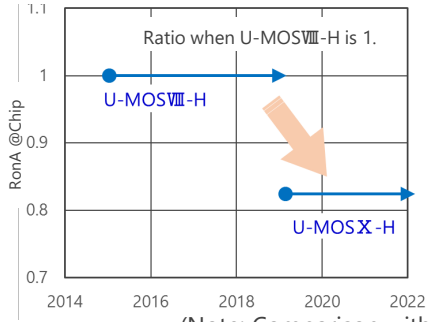
1 Low loss (reduced on-resistance)

Using low on-resistance technology to contribute to reduced power consumption systems.
On-resistance per unit area has been reduced by 18 %.
(compared to Toshiba's U-MOSⅧ-H products)

2 Small and high power dissipation package

The small and high power dissipation packages are developed by adopting Cu clip or Cu connector structure.
Wettable Flank (WF) package contributes to good mountability.

Low loss: RonA reduction trend



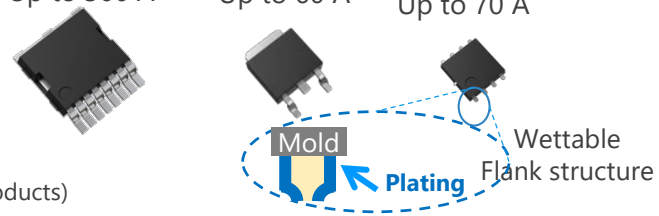
(Note: Comparison with Toshiba products)

Small and high power dissipation package

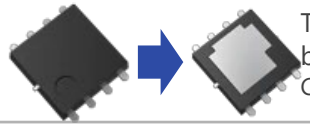
L-TOGL™ (9.9 x 11.8 mm) Up to 300 A

DPAK+ (6.5 x 10 mm) Up to 60 A

SOP Advance(WF) (5 x 6 mm) Up to 70 A



DSOP Advance(WF)L double-sided cooling packages



Thermal resistance is reduced by 76 % @t = 3 s, mounted on board
Compared to Toshiba's SOP Advance(WF)

L-TOGL™ Cu clip structure

Lineup

Part number	Rated drain current [A]	On-resistance (Max) [mΩ] @V_{GS} = 10 V	Package
XPN1300ANC	30	13.3	TSON Advance(WF)
XPN2400ANC *	(20)	(23.5)	
TK60S10N1L	60	6.11	DPAK+
XPH4R10ANB	70	4.1	SOP Advance(WF)
XPH6R30ANB	45	6.3	
XPW4R10ANB	70	4.1	DSOP Advance(WF)L
XPW6R30ANB	45	6.3	DSOP Advance(WF)M
XPQ1R00AQB *	(300)	(1.03)	L-TOGL™

* : Under development (Values enclosed in parentheses are tentative specifications. Specifications are subject to change without notice.)

◆Return to Block Diagram TOP

3 Gate driver (for motor)

TPD7211F / TPD7212F / TPD7212FN

Robustness | High efficiency · Low loss | Small size package

Value provided

The high gate drive current capability reduces MOSFET losses and improves the efficiency of system.

1 High gate drive current

High drive current capability and high speed switching contribute to reduce the loss.

TPD7211F: ±0.5 A

TPD7212F, TPD7212FN: -1 / +1.5 A

2 Built-in protection / diagnostic output function

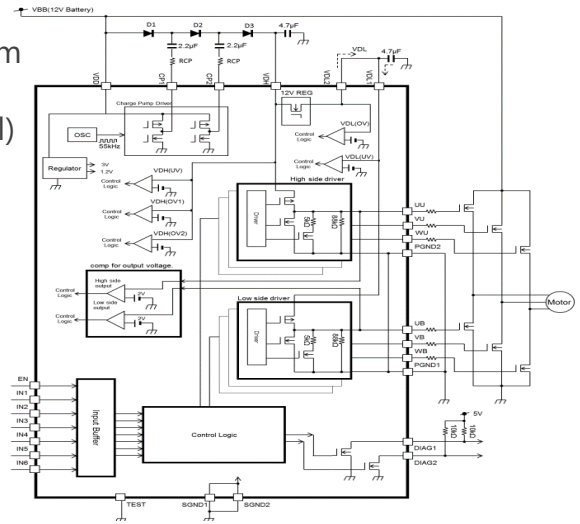
MOSFET is turn off when a signal is input that causes arm short circuit.

Functions to monitor abnormalities of the power supply voltage and output voltage are built-in.

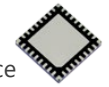
3 Small surface mount package

PS-8, WQFN32 and SSOP30 are small surface mount packages. They contribute to the miniaturization of system.

Example of application and block diagram of TPD7212F, TPD7212FN
(Three phase brushless DC motor control)



Lineup

Part number	TPD7211F	TPD7212F / TPD7212FN
Function	Half bridge output gate driver	Gate driver for three-phase brushless motor
Number of output	2 outputs	6 outputs
Package	 PS-8 (2.8 x 2.9 mm)	TPD7212F  Back surface P-WQFN32-0505-0.50-002 TPD7212FN  SSOP30-P-300-0.65
Features	・For high side P-ch MOSFET drive	・For driving high side N-ch MOSFET (with built-in charge pumps) ・Built-in voltage monitoring function (power supply, output)

◆Return to Block Diagram TOP

4a Brushless DC motor pre driver for blower

TB9080FG

Robustness | High efficiency · Low loss | Small size package

Value provided

This is suitable for applications as air conditioner blower motors or battery cooling fans, that required quietness and high efficiency.

1 Support two types of rotation control input

The motor speed control is compatible with both PWM [Note] signal input and DC voltage input.

[Note] Pulse Width Modulation

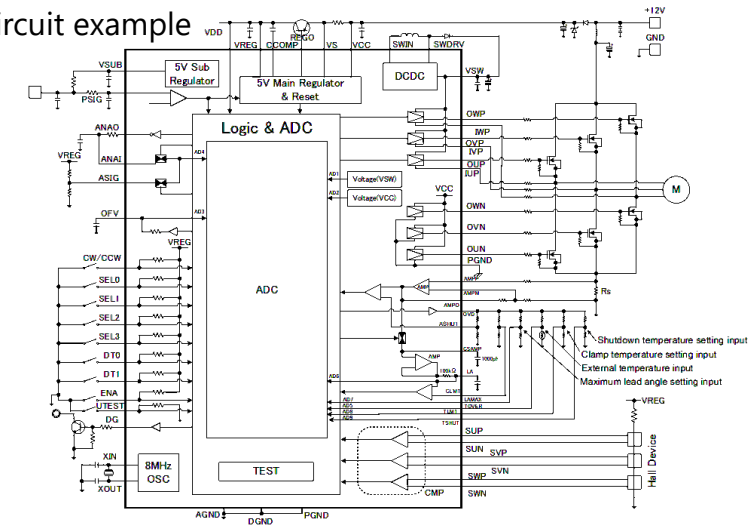
2 No microcontroller required

Since a microcontroller is not required, the area of control board can be reduced and the program development period can be shortened.

3 Various built-in detection functions

Built-in various detection functions such as overcurrent, overtemperature, over voltage, and under voltage.

Application circuit example



Lineup

Part number	TB9080FG
Package	LQFP64-P-1010-0.50E (12 x 12 mm) 
Operating voltage range [V]	7 to 18
Sleep consumption current (Typ.) [μA]	50
Number of external MOSFETs	N-ch x 6
Drive control	Sine wave control

◆Return to Block Diagram TOP

4b Brushed DC motor driver for damper

TB9101FNG / TB9102FNG

Robustness | High efficiency · Low loss | Small size package

Value provided

It has built-in output MOSFETs and can drive brushed DC motor directly.

1 Built-in output MOSFETs

It has built-in output MOSFETs and can drive brushed DC motor directly.

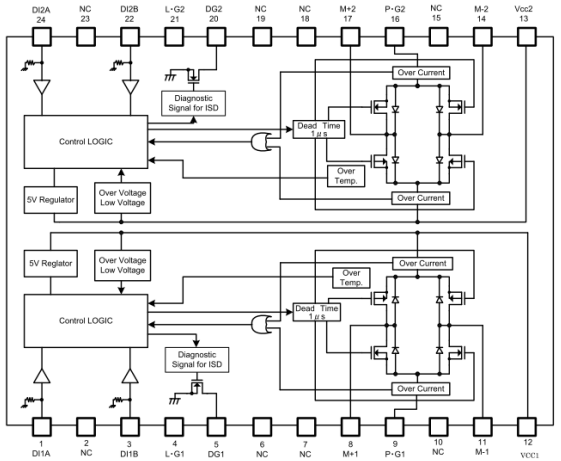
2 Low on-resistance

Low on-resistance contributes to reduce heat generation and power consumption.

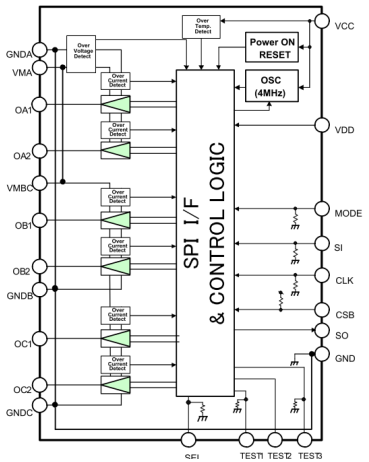
3 Various built-in detection functions

Built-in various detection functions such as overcurrent, overtemperature, over voltage and under voltage.

TB9101FNG block diagram



TB9102FNG block diagram



Lineup

Part number	TB9101FNG	TB9102FNG
Package	SSOP24-P-300-0.65A (7.6 x 8.3 mm)	
Power supply voltage [V]	7 to 18	7 to 18
Output current [A]	±1.0	±1.0
Allowable power dissipation [W]	1.32	1.32
On-resistance (High side / Low side) (Typ.) [Ω]	0.6 / 0.6	0.5 / 0.5
External interface	Direct input	SPI interface

◆Return to Block Diagram TOP

4c Brushed DC motor driver for damper

TB9056FNG / TB9058FNG

Robustness | High efficiency · Low loss | Small size package

Value provided

This is full hardware brushed DC motor driver with LIN communication function.

1 Simple control by full hardware

No need to develop software.
Motor control by LIN communication (slave).

2 Low on-resistance and low standby current

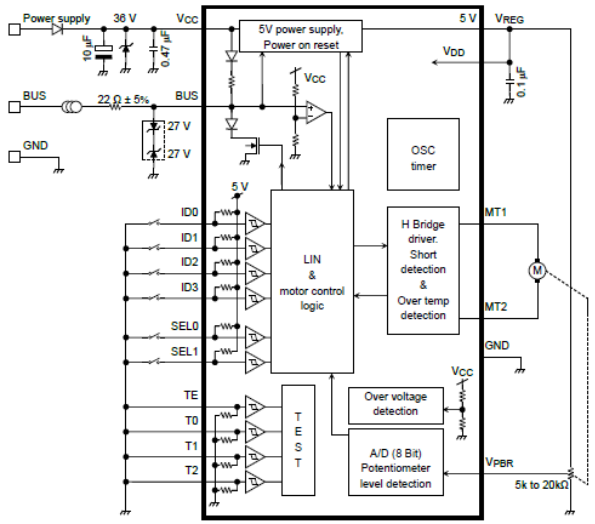
On-resistance: 2.2 Ω (Typ.)
(High side + Low side)

Standby current: 10 μA (Max)

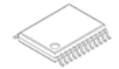
3 Various built-in detection functions

Built-in various detection functions such as over current, over temperature, over voltage and under voltage.

TB9056FNG /
TB9058FNG block diagram



Lineup

Part number	TB9056FNG	TB9058FNG
Package	SSOP24-P-300-0.65A 	
Power supply voltage [V]	7 to 18	7 to 18
Output current [A]	0.3	0.3
Motor drive circuit type	H-bridge (1ch)	H-bridge (1ch)
On-resistance (High side / Low side) (Typ.) [Ω]	1.0 / 1.2	1.0 / 1.2
Communication method	LIN rev. 1.3	LIN rev. 1.3 (Enhanced checksum)

◆Return to Block Diagram TOP

4d Stepping motor driver

TB9120AFTG

Robustness | High efficiency · Low loss | Small size package

Value provided

Micro stepping drive controlled by single clock input signal only.

1 Micro stepping drive

Full step to 1/32 step which contributes to reducing noise and vibration is supported.
Neither high performance MCUs nor software are required. It can be controlled by clock signal.

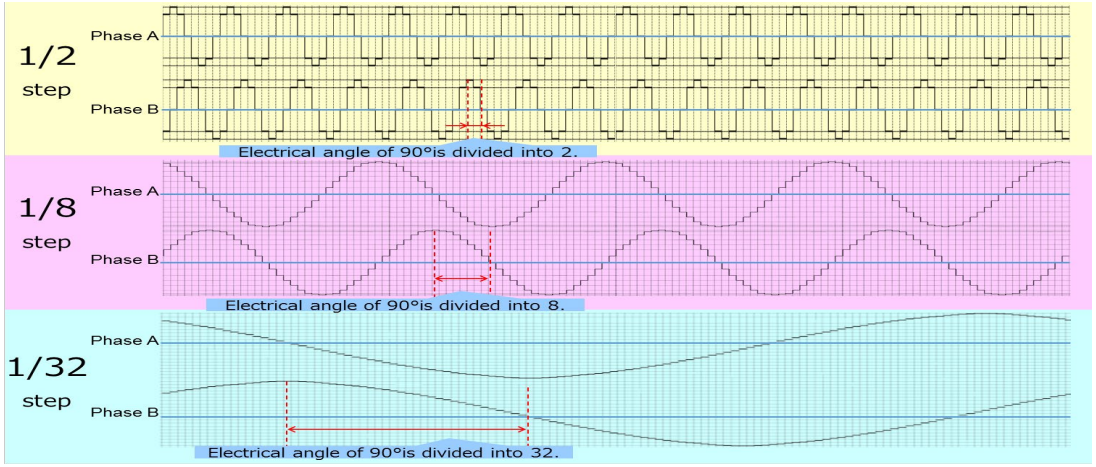
2 Stall detection

A detection signal is output, if the IC judges a malrotation.

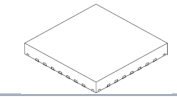
3 Broad utility

It can be used for various applications.
Application example
- Dampers
- Expansion valves
- Head-up Display (HUD)

Current waveform in micro step



Lineup

Part number	TB9120AFTG
Package	P-VQFN28-0606-0.65-002 6 x 6 mm Wettable flank package contributes to good solderability. 
Output device	Built-in MOSFETs for 1 A class
Output MOSFET on-resistance	0.8 Ω (Typ.) (High side + Low side, Ta = 25 °C)
Detection circuit	Over current, over temp., stall detection and load open
Standby function	Current consumption less than 10 μA in standby mode Built-in a standby pin

◆Return to Block Diagram TOP

5 U-MOS Series -40 V / -60 V P-ch MOSFET

XPN9R614MC / XPH3R114MC / XPH8R316MC* / TJ90S04M3L

Robustness | High efficiency · Low loss | Small size package

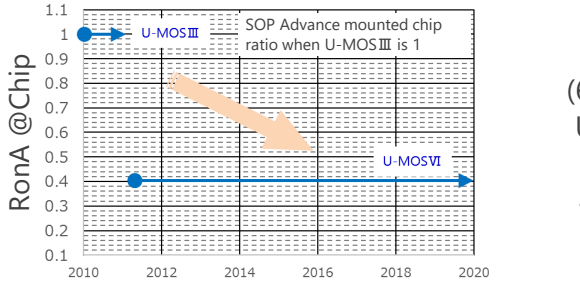
Value provided

Low on-resistance contributes to reduce system power consumption.

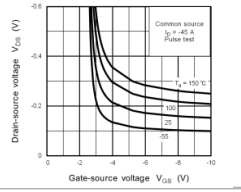
1 Low loss (reduced on-resistance) and logic level drive

Using a low on-resistance technology contributes to reduce system power consumption.
A lineup of logic level drive type is supported.
The on-resistance per area is reduced by 60 %.
(compared to Toshiba's U-MOSⅢ products)

Low loss: RonA reduction trend



(Note: Comparison with Toshiba products)



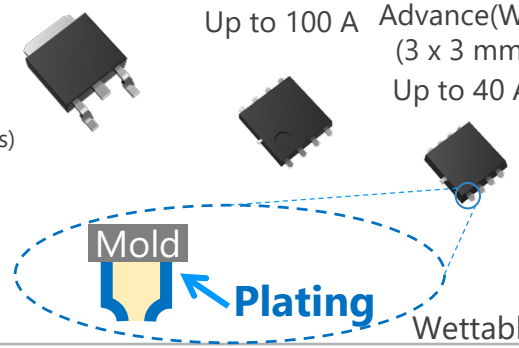
Logic level drive
TJ90S04M3L
V_{DS} - V_{GS}

Large current, small size, high power dissipation package

DPAK+
(6.5 x 9.5 mm)
Up to 90 A

SOP Advance(WF)
(5 x 6 mm)
Up to 100 A

TSON Advance(WF)
(3 x 3 mm)
Up to 40 A



Wettable Flank (WF) structure

2 Small and low loss packages

By adopting a Cu connector structure, a low loss and high power dissipation package is realized.
Wettable Flank (WF) package contributes to good mountability.

Lineup

Part number	Rated drain-source voltage [V]	Rated drain current [A]	On-resistance (Max) [mΩ] @V_{GS} = -10 V	Package
XPN9R614MC	-40	-40	9.6	TSON Advance(WF)
XPH3R114MC	-40	-100	3.1	SOP Advance(WF)
XPH8R316MC*	-60	(-90)	(8.3)	
TJ90S04M3L	-40	-90	4.3	DPAK+

* : Under development (Values enclosed in parentheses are tentative specifications. Specifications are subject to change without notice.)

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6 General purpose small signal MOSFET

SSM3K7002KF / SSM3J168F / SSM3J66MFV

Robustness | High efficiency · Low loss | Small size package

Value provided

Wide lineup of small packages contribute to reduce the size and power consumption of system.

1 Small package

A lineup of various small packages such as SOT-723 (VESM 1.2 x 1.2 mm package) is available, contributing to reduce mounting area.

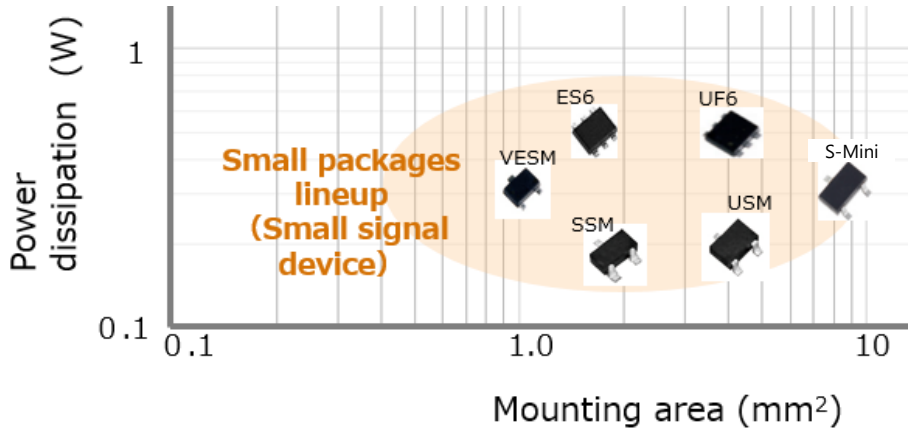
2 Low voltage drive

SSM3J66MFV can be driven at low gate-source voltage of 1.2 V.

3 AEC-Q101 qualified

AEC-Q101 qualified and can be used for various automotive applications.

Small signal package lineup



Lineup

Part number		SSM3K7002KF	SSM3J168F	SSM3J66MFV
Package		S-Mini (SOT-346)	S-Mini (SOT-346)	VESM (SOT-723)
V_{DSS} [V]		60	-60	-20
I_D [A]		0.4	-0.4	-0.8
$R_{DS(ON)}$ @$\|V_{GS}\|$ = 4.5 V [Ω]	Typ.	1.2	1.4	0.31
	Max	1.75	1.9	0.39
Drive voltage [V]		4.5	-4.0	-1.2
Polarity		N-ch	P-ch	P-ch

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7 General purpose small signal bipolar transistor

2SC2712 / 2SA1162 / 2SC4116 / 2SA1586 / TTA501 / TTC501 and others

Robustness | High efficiency · Low loss | Small size package

Value provided

Extensive product lineup to meet customers' needs.

1 Extensive lineup of packages

Various packages such as 1-in-1, 2-in-1 are provided and suitable products for circuit board design are selectable.

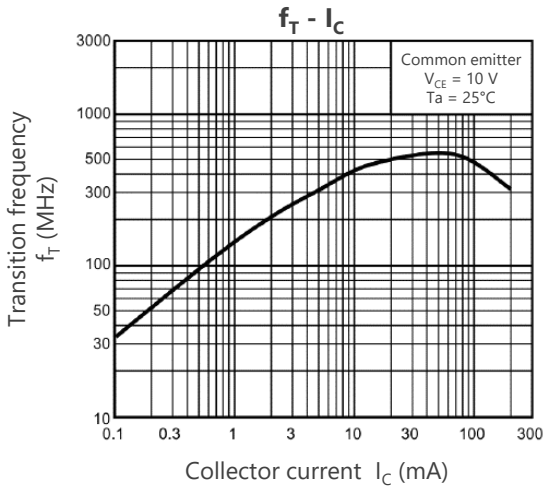
2 Extensive product lineup

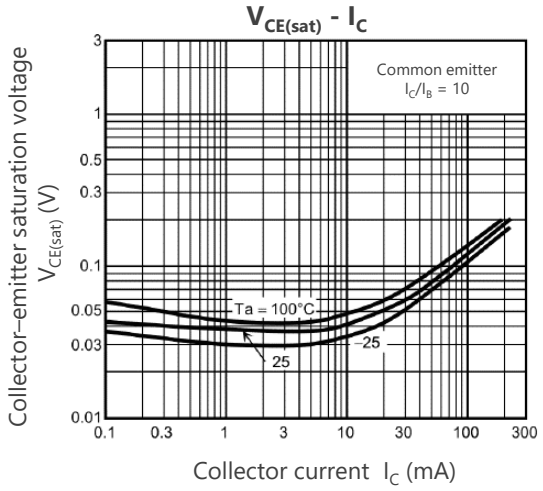
Various product lineups, such as general purpose, low noise, low $V_{CE(sat)}$ and high current types are provided. Products can be selected in accordance with the application.

3 AEC-Q101 qualified

AEC-Q101 qualified and can be used for various automotive applications.

Characteristic examples of 2SC2712





Lineup

Package			SOT-23F		USM (SOT-323) UFM (SOT-323F)*		S-Mini (SOT-346)	
Classification	| V_{CEO} | [V]	| I_C | [mA]	NPN	PNP	NPN	PNP	NPN	PNP
General purpose	50	150			2SC4116	2SA1586	2SC2712	2SA1162
	50	500					2SC3325	2SA1313
Low noise	120	100			2SC4117	2SA1587	2SC2713	2SA1163
High current	50	1700				2SA2195*		
	50	2000		TTA501				
	50	2500	TTC501					

* indicates UFM package

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8 Gate driver (for switch)

TPD7104AF / TPD7106F / TPD7107F

Robustness | High efficiency · Low loss | Small size package

Value provided

A charge pump circuit for the N-ch MOSFET gate drive is built in, allowing for easy semiconductor relay configuration.

1 Built-in charge pump circuit

Built-in charge pump circuit enables N-ch MOSFET as high side switch.
Easy to configure a semiconductor relay.

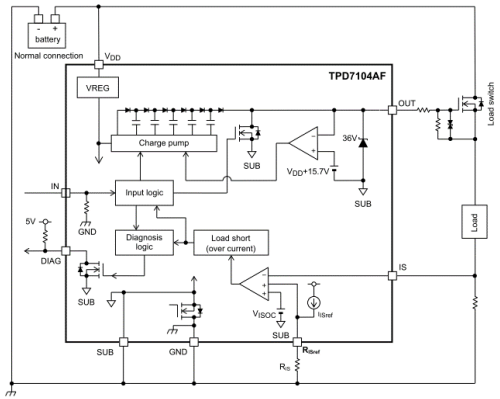
2 Can be controlled by logic level voltage

It is possible to be controlled directly by output signal of MCUs or CMOS logic ICs.

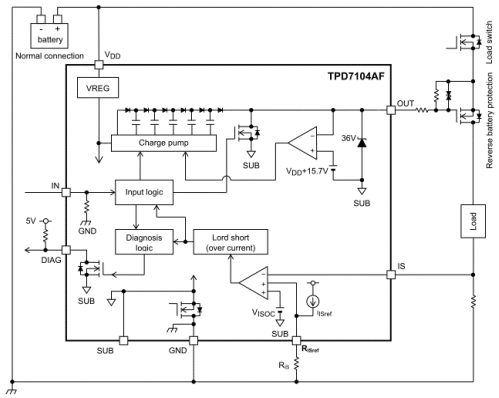
3 Small package

The small surface mount packages such as PS-8, SSOP16 and WSON10A contribute to the miniaturization of equipment.

Semiconductor relay (switch) application (TPD7104AF)



Power supply reverse connection protection MOSFET control (TPD7104AF)



Back to back configuration

Lineup

Part number	TPD7104AF	TPD7106F	TPD7107F
Package	PS-8 (2.8 x 2.9 mm)	SSOP16 (5.5 x 6.4 mm)	WSON10A (3 x 3 mm)
Function	High side gate driver	High side gate driver	High side gate driver
Output	1	1	1
Features	・Operating power supply voltage range: 5 to 18 V ・Built-in power supply reverse connection protection function (Protective MOSFET control with back-to-back circuitry)	・Operating power supply voltage range: 4.5 to 27 V ・Built-in power supply reverse connection protection function (Protective MOSFET control with back-to-back circuitry)	・Operating power supply voltage range: 5.75 to 26 V ・Current sense output ・Protective functions; overcurrent, overtemperature, GND disconnect, etc. reverse battery connection ・Diagnosis output; overcurrent, load open, overtemperature, etc.

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9 Small signal bias resistor built-in transistor (BRT)

RN1907FE / RN2907FE / RN1901 / RN2901 Series

Robustness | High efficiency · Low loss | Small size package

Value provided

Extensive product lineup to meet customers' needs.

1 Built-in bias resistor type
(BRT : Bias Resistor built-in Transistor)

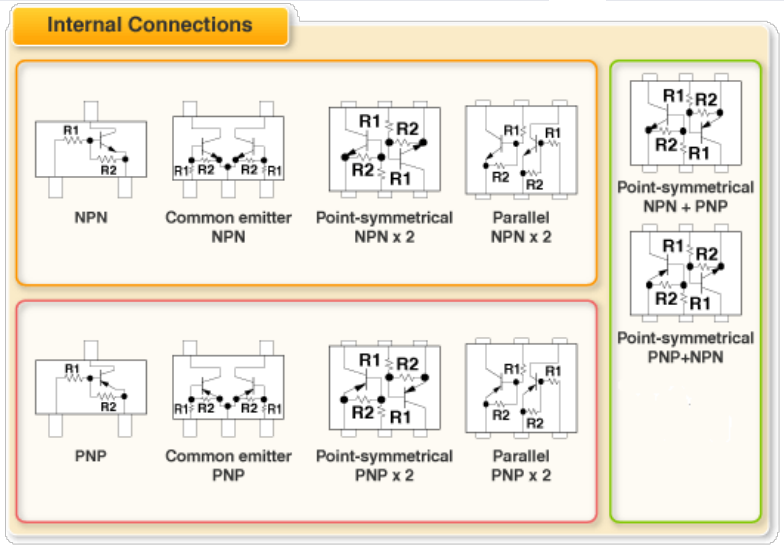
The BRTs contribute to reduction of the number of components, assembly workload and mounting area of circuit boards.

2 Extensive lineup of package and pin assignment

Various package lineups, such as 1-in-1, 2-in-1 and various pin assignment type are provided and suitable products for circuit board design are selectable.

3 AEC-Q101 qualified

AEC-Q101 qualified and can be used for various automotive applications.



Lineup

Part number		NPN (BRT)	PNP (BRT)
Package	ES6 (SOT-563)	RN1907FE	RN2907FE
	US6 (SOT-363)	RN1901	RN2901
V_{CEO} [V]		50	-50
I_C [mA]		100	-100

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10 TVS diode (for CAN communication)

DF3D18FU / DF3D29FU / DF3D36FU

Robustness | High efficiency · Low loss | Small size package

Value provided

TVS diodes prevent system damage and malfunction caused by electrostatic discharge (ESD).

1 Improve ESD pulse absorbability

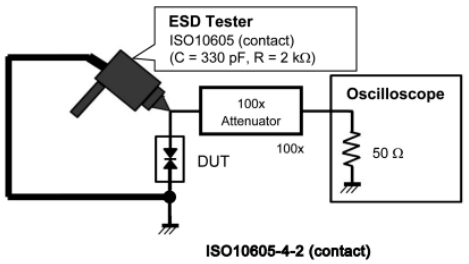
Toshiba proprietary Zener process improves the ESD pulse absorption of TVS diodes.
(Achieving both low dynamic resistance R_{DYN} and low capacitance between terminals C_t)

2 Supports CAN, CAN FD and FlexRay

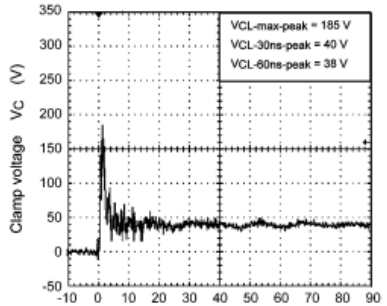
These are products applicable to in-vehicle LAN communication such as CAN, CAN FD and FlexRay.

3 High ESD immunity

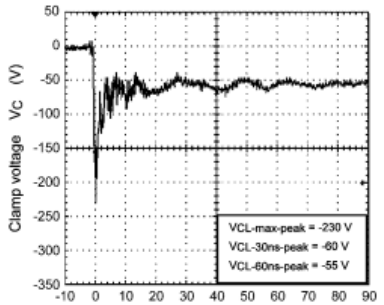
V_{ESD} > ±30 kV @ISO 10605
V_{ESD} > ±20 kV @IEC 61000-4-2 (Level 4)



ISO10605-4-2 (contact)



DF3D36FU +15kv (ISO10605)



DF3D36FU -15 kV (ISO10605)

Lineup

Part number	DF3D18FU	DF3D29FU	DF3D36FU
Package	USM (SOT-323) 		
V_{ESD} [kV] @ISO 10605	±30	±30	±20
V_{RWM} (Max) [V]	12	24	28
C_t (Typ. / Max) [pF]	9 / 10		6.5 / 8
R_{DYN} (Typ.) [Ω]	0.8	1.1	1.5

(Note) The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.
This product is an ESD protection diode and cannot be used for purposes other than ESD protection.

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11 Power supply IC (for MCU)

TB9005FNG

Robustness | High efficiency · Low loss | Small size package

Value provided

This is voltage regulator with low current consumption, and various monitoring functions such as WDT [Note] contribute to improving system stability.

[Note] Watchdog Timer

1 Low current consumption

External transistor type voltage regulator with low current consumption.
Load stability is 1 % (Max) (@ILOAD = 1 to 300 mA) .

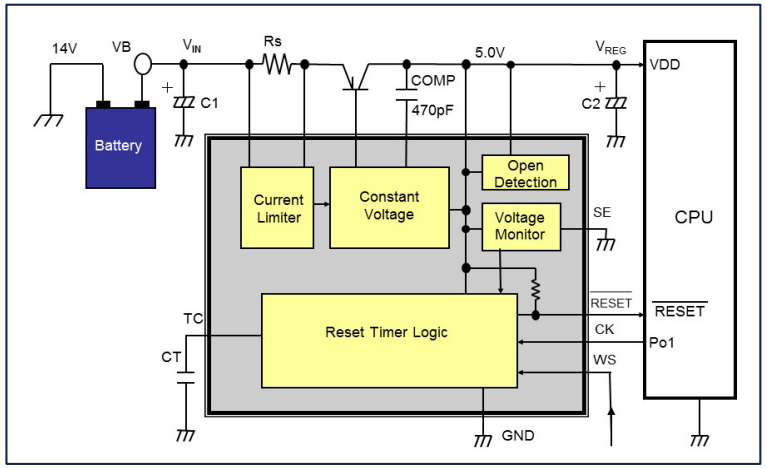
2 Built-in WDT and various monitoring functions

The WDT monitors the operation of the MCU.
In addition, current detection functions contribute to improving system stability.

3 AEC-Q100 qualified

It is AEC-Q100 qualified and can be used for various automotive applications.

Application circuit example (The current limiter can be adjusted by an external resistor.)



Lineup

Part number		TB9005FNG
Package		SSOP20-P-225-0.65A (6.4 x 7.0 mm)
Current consumption I_{CC} (Typ.) [μA]		90 (@V_{IN} = 12 V, Ta = 25 °C)
Load stability VLOAD (Max) [%]		1 (@ILOAD = 1 to 300 mA)
Function	Number of outputs	1ch (5 V)
	Circuit type	External transistor type
	WDT, Overcurrent limitation	✓

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